FEB 2 7 2004 No. 42390P10075

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re Patent Application of:) Enguines Andrian I
Harry Q. Pon Application No.: 09/822,944) Examiner: Andujar, L.) Art Unit: 2826)
Filed: March 30, 2001)
For: INSULATED BOND WIRE ASSEMBLY PROCESS TECHNOLOGY FOR INTEGRATED CIRCUITS))))
Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450 AMENDMENT	$oldsymbol{\Gamma}$
Sir:	
In response to the Office Action mailed November 20, 2003, please amend the above-	
identified application as follows.	
Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.	
Remarks/Arguments begin on page 6 of this paper.	

I hereby state that this correspondence is being deposited with the United States Postal Service as first class mail with sufficient postage in an envelope addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, Virginia 22313-1450 on

February 20, 2004

Date of Deposit

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